



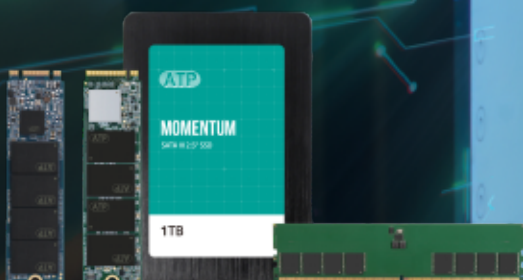
The Global Leader in Specialized Storage and Memory Solutions

WE BUILD WITH YOU

ATP MOMENTUM LINE STORAGE AND MEMORY SOLUTIONS

Emphasizing rapid time-to-market, broad compatibility, and cost-efficient storage, the ATP Momentum Line combines cutting-edge technology with essential solutions tailored to meet the diverse needs of the industrial market. With ATP's commitment to quality control and rigorous verification processes, our products consistently deliver dependable results.

Offering a range of mainstream specifications and storage capacities, the ATP Momentum Line provides versatile options for various industrial applications.



PRODUCT FLYER

Momentum Line SSDs Overview:

- Extended-Commercial Temp Operable (-20°C to 75°C)
- Ideal for Write-Moderate, Read-Intensive applications
- DRAM-less power-efficient design
- Data-at-rest power loss protection (Firmware-based)

Targeted Market Segments for the Momentum Line SSDs

Ideal for Write-Moderate, Read-Intensive applications



ATP Momentum Line SSDs

PCIe® Gen4 NVMe M.2 2280 SSD



N601Mw

- PCIe Gen4 x4, NVMe 1.4
- 256 GB to 4 TB capacities
- Extended-Commercial Temp Operable (-20°C to 75°C)
- Power loss protection for data at rest
- AutoRefresh and Auto-Read Calibration elevate runtime data integrity
- End-to-End Data Path Protection
- Host Memory Buffer (HMB) support

PCIe® Gen3 NVMe M.2 2280 SSD



N400Mw

- PCIe Gen3 x4, NVMe 1.3
- 128 GB to 1 TB capacities
- Extended-Commercial Temp Operable (-20°C to 75°C)
- Power loss protection for data at rest
- AutoRefresh and Auto-Read Calibration elevate runtime data integrity
- End-to-End Data Path Protection
- Host Memory Buffer (HMB) support

SATA III M.2 2280 SSD / 2.5" SSD



A400Mw

- SATA III 6 Gb/s
- 128 GB to 1 TB capacities
- Extended-Commercial Temp Operable (-20°C to 75°C)
- Power loss protection for data at rest
- SSD features built with ATP expertise for comprehensive reliability
- Power-efficient DRAM-less design

Product Line	Momentum			
	N601Mw	N400Mw	A400Mw	A400Mw
Interface	PCIe G4 x4	PCIe G3 x4	SATA III 6 Gb/s	SATA III 6 Gb/s
Flash Type	3D TLC			
Form Factor	M.2 2280 S3-M	M.2 2280 S2-M	M.2 2280 S2-B-M	2.5"
Operating Temperature	-20°C to 75°C			
Power Loss Protection Options	Firmware Based			
Optional SED Features	-			
Capacity	256 GB to 4 TB	128 GB to 1 TB		
Performance				
Sequential Read (MB/s) up to	7,200	2,600	550	550
Sequential Write (MB/s) up to	6,500	1,800	500	500
Random Reads IOPS up to	1,000,000	240,000	72,000	72,000
Random Writes IOPS up to	1,200,000	300,000	86,000	86,000
Endurance and Reliability				
Endurance (TBW) ¹ up to	6,000 TB	695 TB	765 TB	765 TB
Reliability MTBF @ 25°C	>3,000,000 hours			
Others				
Dimensions (mm)	80.0 x 22.0 x 2.2			100 x 69.85 x 7
Certifications	CE, FCC, BSMI, UKCA, RoHS, REACH			
Warranty	2 years			

ATP Momentum DRAM Series : DDR4/DDR5

The new Momentum Series industrial DRAM modules offer mainstream data transfer rates combined with a low power consumption, ensuring faster performance and greater power savings. They adhere to all JEDEC standards and utilize top-tier DRAM chips to provide high levels of reliability, compatibility, and stability across various industrial applications. With ATP's commitment to quality control and rigorous verification processes, these modules consistently deliver dependable results.



KEY FEATURES

- Densities: 8 GB to 32 GB
- JEDEC Compliant
- Top-tier DRAM chips and production traceability
- Decreased voltage for better power efficiency
- Unique ATP TDBI decreases error rate over time
- Designed and validated for confident data integrity and compatibility
- Operating Temperature: 0°C to 85°C

MOMENTUM DRAM MODULES ARE IDEAL FOR USE IN:

- Industrial PCs
- Retail/point-of-sale systems (POS)
- Kiosks/Digital Signages
- Casino Gaming
- Thin-client PCs
- Automation
- ATM
- Medical & Healthcare

Product	DIMM Type	Density	Speed (MT/s, up to)	Operating Temp.	PCB Height	Part Number	ATP TDBI	Wide Temperature
DDR5	Non-ECC UDIMM	8 GB	5600	0°C to 85°C	Low Profile	R58G00UD566CAYC	●	▲
		16 GB	5600	0°C to 85°C	Low Profile	R516G0UD568AAYC	●	▲
		32 GB	5600	0°C to 85°C	Low Profile	R532G0UD568BAYC	●	▲
	Non-ECC SO-DIMM	8 GB	5600	0°C to 85°C	Low Profile	R58G00SD566CAYC	●	▲
		16 GB	5600	0°C to 85°C	Low Profile	R516G0SD568AAYC	●	▲
		32 GB	5600	0°C to 85°C	Low Profile	R532G0SD568BAYC	●	▲
DDR4	Non-ECC UDIMM	8 GB	3200	0°C to 85°C	Low Profile	R48G00UD328AGSC	●	▲
		16 GB	3200	0°C to 85°C	Low Profile	R416G0UD328BGSC	●	▲
		32 GB	3200	0°C to 85°C	Low Profile	R432G0UD328BCSC	●	▲
	Non-ECC SO-DIMM	8 GB	3200	0°C to 85°C	Low Profile	R48G00SD328AGSC	●	▲
		16 GB	3200	0°C to 85°C	Low Profile	R416G0SD328EGSC	●	▲
		32 GB	3200	0°C to 85°C	Low Profile	R432G0SD3282CSC	●	▲

▲: Optional



The Global Leader in Specialized Storage and Memory Solutions

WE BUILD WITH YOU

Follow us on

ATP Website



www.atpinc.com

ATP TAIWAN Headquarters

TEL: +886-2-2659-6368
FAX: +886-2-2659-4982
sales-apac@atpinc.com
10F, No. 185, Tiding Blvd. Sec. 2,
Neihu, Taipei, Taiwan 11493

ATP USA

TEL: +1-408-732-5000
FAX: +1-408-732-5055
sales@atpinc.com
2590 North First Street,
Suite #150, San Jose, CA 95131, USA

ATP INDIA

sales-india@atpinc.com

ATP JAPAN

TEL: +81-3-6260-0797
FAX: +81-3-6260-0798
sales-japan@atpinc.com
Daimon Urbanist 602, 2-3-6 Shiba Daimon,
Minato-ku, Tokyo 105-0012, Japan

ATP EUROPE

TEL: +49-89-374-9999-0
FAX: +49-89-374-9999-29
sales-europe@atpinc.com
Max-Planck-Str. 5,
D-85716 Unterschleißheim, Germany

ATP CHINA

TEL: +86-21-5080-2220
FAX: +86-21-9687-0000-026
sales@cn.atpinc.com
2F, Building 15, No. 115, Lane 572,
Bibo Road, Zhangjiang High-Tech Park
Pudong, Shanghai, China 201203

v2 052025

© Copyright 2025 ATP Electronics, Inc. All rights reserved.

Specifications or details may change without notice.

All trademarks and registered trademarks are the property of their respective owners.

Printed on fully recyclable paper.